

# GS600SU Underfill Dispensing Machine FCBGA, FCCSP, SIP Die Form Underfill Die Form Underfill

# **Basic Information**

- Place of Origin:
- Brand Name:
- Certification:
- Model Number:
- Minimum Order Quantity:
- Price:
- Packaging Details:
- Delivery Time:
- Payment Terms:
- GS600SU 1 \$28000-\$150000 WOODEN 5-60 days L/C, T/T, D/A, D/P, MoneyGram, Western Union



## **Product Specification**

Condition:	New	
Warranty:	1 Year	
<ul> <li>Product Name:</li> </ul>	GS600SU Underfill Dispensing Machine	
<ul> <li>Application Fields:</li> </ul>	FCBGA, FCCSP, Sip	
<ul> <li>Applicable Process:</li> </ul>	Die Form Underfill	
<ul> <li>Cleanliness Level:</li> </ul>	Cleanliness Of Working Area	
Transmission System:	X/Y:Linear Motor Z Servo Motor&Screw Module	
• Repeatability (3sigma)X/Y:	X/Y ±0.003mm Z ±0.005mm	
<ul> <li>Positioning Accuracy (3sigma):</li> </ul>	X/Y ±0.010mm Z ±0.015mm	
Max. Movement Speed:	X/Y 1000mm/s Z 500mm/s	
Max. Accelerated Velocity:	X/Y 1g Z 0.5g	
<ul> <li>Grating Resolution:</li> </ul>	1µ M	
<ul> <li>Z Axis Movement Range(W×D):</li> </ul>	350mm×470mm	

China

ISO

MingSeal



### **GS600SU Underfill Dispensing Machine**

### For Die Form Underfill

GS600 SU is a high- speed and high- precision automatic online dispensing system which is developed based on Underfill process requirements of FCBGA/FCCSP.

The system strictly controls the product and adhesive temperature, and intelligently sorts the product operation sequence and the glue replenishment time, reducing the generation of voids and ensuring the operation yield. Meanwhile, it is compatible with international semiconductor communication protocols, and matches the infor- mation management requirements.

#### Application Fields

FCBGA Packaging CUF Application FCCSP Packaging CUF Application SiP Packaging CUF Application

Technical	Specifications	
Application	ECEGA ECCSP SIP	
Fields	רטטטר, אד 	
Applicable	Die Form Underfill	
Process		1
Cleanliness	Cleanliness of working area	Class 100 (Class 1000 workshop)
Level Transmission Mechanism		Class 10 (Class 100 workshop)
	Transmission system	X/Y:Linear motor Z: Servo motor&Screw module
	Repeatability (3sigma)	X/Y: ±0.003mm, Z: ±0.005mm
	Positioning accuracy (3sigma)	X/Y: ±0.010mm, Z: ±0.015mm
	Max. movement speed	X/Y: 1000mm/s
		Z: 500mm/s
	Max. accelerated velocity	X/Y: 1g, Z: 0.5g
	Grating resolution	1 µ m
	Z axis movement range(W× D)	3 5 0 mm×4 7 0mm
	Z axis height calibration & compensation Method	Laser sensor (Laser sensor)
	Laser sensor accuracy	2μ m
	Glue control accuracy	± 3 % / 1mg
	Single dot position repeatability CPK 1.0	±25 μ m
	Min. nozzle diameter	30 µ m
	Min. single dot glue weight	0 .001mg/dot
	Max. fluid viscosity	200000cps
	Max. jetting frequency	1000Hz
	Runner/nozzle heating temperature	Room temperature~200°C
Dispensing	Runner/nozzle heating temp. deviation	± 2 ℃
System	Applicable adhesive packaging spec.	5CC/10CC/30CC/50CC/70CC
	Syringe cooling range	Cools down to 15°C below ambient temp.
	Piezo cooling range	Cools down to compressed air source temp.
	Number of tracks	2
Track System	Number of belt sections	One piece
	Max. track transmission speed	300mm/s
	Max. track transmission weight	Зка
	Minimum edge clearance	3 mm
	Track width adjustment range	60mm~ 162mm Adjustable
	Track width adjustment Method	Manual
	Track beight	910mm~960mm Adjustable
	substrate/carrier	6 mm
	Applicable substrate/carrier length range	60mm-325mm
	Vacuum suction pressure Bange	-50~-80Kpa Adjustable
	Bottom beating temperature range	Boom temperature~180°C
	Bottom heating temperature range	<+1.5℃
		2380mm*1550mm*2080mm(Loading&Lloloading& display
	Footpri nt W× D× H	included)
		2380mm*1200mm*2080mm(Loading&Unloading included
		display excluded)
	Weight	1600kg
		200~240VAC.47~63HZ (Single-phase voltage adaptation power
	Power supply	supply)
	Electric current	30A
	Power	6.4KW
	Inhale	(0.5Mpa, 450L/min) ×2

FCBGA Packaging CUF Application FCCSP Packaging CUF Application SiP Packaging CUF Application

**Special Process Modules** 



#### CUF Special Piezoelectric Jetting System

Adhesive insulation + piezoelectric ceramic temperature closed-loop control to avoid system instability caused by temperature



Triple Low-level Alarm Capacitive detection + magnetic detection + system weighing to avoid poor operation caused by lack of glue



#### Vacuum Adsorption Heating Fixture

The temperature difference of the whole surface of the fixture is  $\leq \pm 1.5$  °C, and the temperature is monitored and compensated in real time to avoid poor operation caused by product temperature variation during operation



### Press-Down Track

The vacuum adsorption fixture always keeps still, and the track moves up and down to avoid poor operation caused by loss of flatness during reciprocating movement of the vacuum adsorption fixture.



Platform-Type Loading & Unloading System The feeding sequence is automatically sorted, and the operation is completed within the Plasma time limit Friendly human-machine interface design



Visual system Positioning and detection functions Inspection before operation to avoid defective incoming materials Inspection after operation to prevent batch defects



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